FAIRCHILD SEMICONDUCTOR®

March 2013

FCH25N60N

N-Channel SupreMOS® MOSFET

600 V, 25 A, 126 mΩ

Features

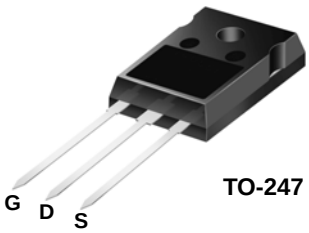
- $R_{DS(on)}$ = 108 mΩ (Typ.)@ V_{GS} = 10 V, I_D = 12.5 A
- Ultra Low Gate Charge (Typ. Qg = 57 nC)
- Low Effective Output Capacitance (Typ. C_{oss}.eff = 262 pF)
- 100% Avalanche Tested
- RoHS Compliant

Applications

- Solar Inverter
- AC-DC Power Supply

Description

The SupreMOS® MOSFET is Fairchild Semiconductor®'s next-generation of high voltage super-junction (SJ) technology employing a deep trench filling process that differentiate it from the conventional MOSFETs. This advanced technology and precise process control provide lowest Rsp on-resistance, superior switching performance and ruggedness. SupreMOS MOSFET is suitable for high frequency switching power converter applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications.



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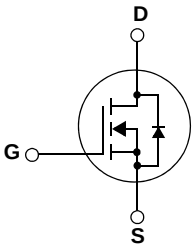


MOSFET Maximum Ratings T_C = 25°C unless otherwise noted*

Symbol	Parameter			FCH25N60N	Unit
V_{DSS}	Drain to Source Voltage			600	V
V_{GSS}	Gate to Source Voltage			±30	V
I_D	Drain Current	Continuous (T_C = 25°C)		25	A
		Continuous (T_C = 100°C)		16	
I_{DM}	Drain Current	Pulsed	(Note 1)	75	A
E_{AS}	Single Pulsed Avalanche Energy		(Note 2)	861	mJ
I_{AR}	Avalanche Current			8.3	A
E_{AR}	Repetitive Avalanche Energy			2.2	mJ
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	20	V/ns
	MOSFET dv/dt			100	
P_D	Power Dissipation	(T_C = 25°C)		216	W
		Derate above 25°C		1.72	W/°C
T_J, T_{STG}	Operating and Storage Temperature Range			-55 to +150	°C
T_L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds			300	°C

*Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FCH25N60N	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.58	°C/W
$R_{\theta CS}$	Thermal Resistance, Case to Heat Sink (Typical)	0.24	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	40	

Package Marking and Ordering Information $T_C = 25^oC$ unless otherwise noted

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FCH25N60N	FCH25N60N	TO247	-	-	30

Electrical Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
BV_{DSS}	Drain to Source Breakdown Voltage	I_D = 1 mA, V_{GS} = 0 V,T_J = 25°C	600	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = 1 mA, Referenced to 25°C	-	0.74	-	V/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 480 V, V_{GS} = 0 V	-	-	10	µA
		V_{DS} = 480 V, T_J = 125°C	-	-	100	
I_{GSS}	Gate to Body Leakage Current	V_{GS} = ±30 V, V_{DS} = 0 V	-	-	±100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS} = V_{DS}, I_D = 250 µA	2.0	-	4.0	V
$R_{DS(on)}$	Static Drain to Source On Resistance	V_{GS} = 10 V, I_D = 12.5 A	-	0.108	0.126	Ω
g_{FS}	Forward Transconductance	V_{DS} = 20 V, I_D = 12.5 A	-		-	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 100 V, V_{GS} = 0 V f = 1 MHz	-	2520	3352	pF
C_{oss}	Output Capacitance		-	103	137	pF
C_{rss}	Reverse Transfer Capacitance		-	3.2	5	pF
C_{oss}	Output Capacitance	V_{DS} = 380 V, V_{GS} = 0V, f = 1 MHz	-	55	-	pF
C_{oss}eff.	Effective Output Capacitance	V_{DS} = 0 V to 480 V, V_{GS} = 0 V	-	262	-	pF
$Q_{g(tot)}$	Total Gate Charge at 10V	V_{DS} = 380 V, I_D = 12.5 A, V_{GS} = 10 V (Note 4)	-	57	74	nC
Q_{gs}	Gate to Source Gate Charge		-	10	-	nC
Q_{gd}	Gate to Drain “Miller” Charge		-	18	-	nC
ESR	Equivalent Series Resistance (G-S)	Drain Open, f = 1 MHz	-	1	-	Ω
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 380 V, I_D = 12.5 A R_G = 4.7 Ω (Note 4)	-	21	52	ns
t_r	Turn-On Rise Time		-	22	54	ns
$t_{d(off)}$	Turn-Off Delay Time		-	68	146	ns
t_f	Turn-Off Fall Time		-	5	20	ns
Drain-Source Diode Characteristics						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	25	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	75	A
V_{SD}	Drain to Source Diode Forward Voltage	V_{GS} = 0 V, I_{SD} = 12.5 A	-	-	1.2	V
t_{rr}	Reverse Recovery Time	V_{GS} = 0 V, I_{SD} = 12.5 A dI_F/dt = 100 A/µs	-	370	-	ns
Q_{rr}	Reverse Recovery Charge		-	7	-	µC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. I_{AS} = 8.3 A, R_G = 25 Ω, Starting T_J = 25°C
3. I_{SD} ≤ 25 A, di/dt ≤ 200 A/µs, V_{DD} ≤ 380 V, Starting T_J = 25°C
4. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

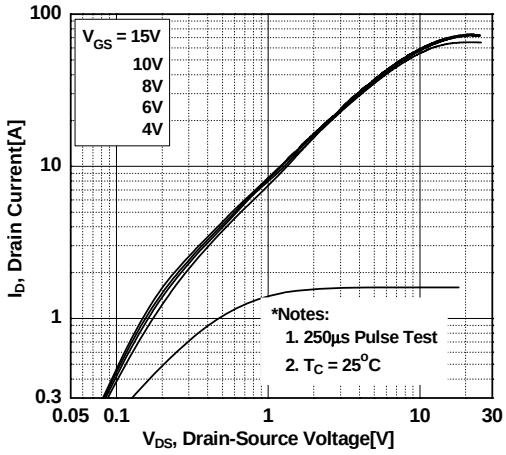


Figure 2. Transfer Characteristics

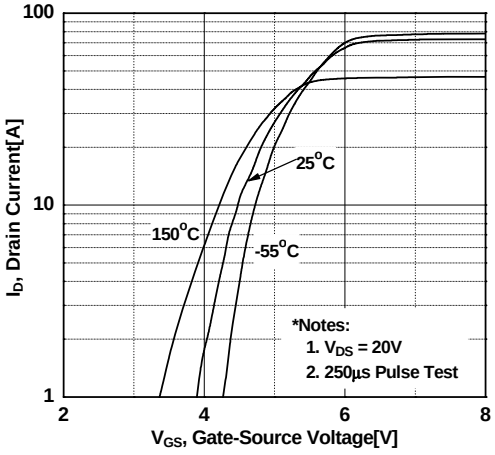


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

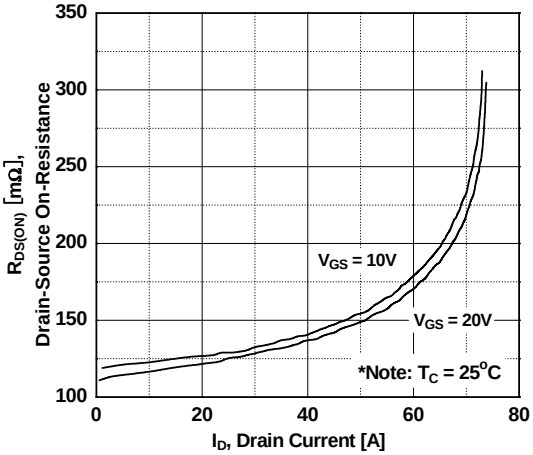


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

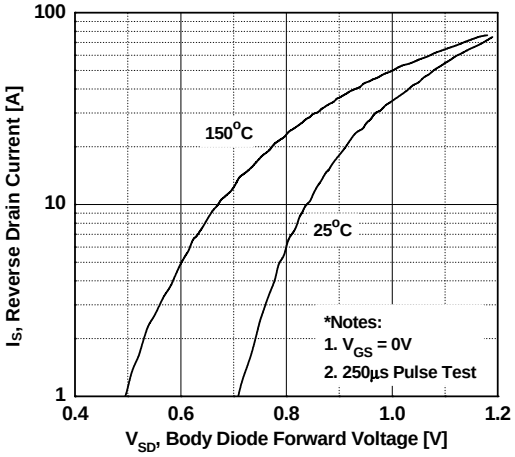


Figure 5. Capacitance Characteristics

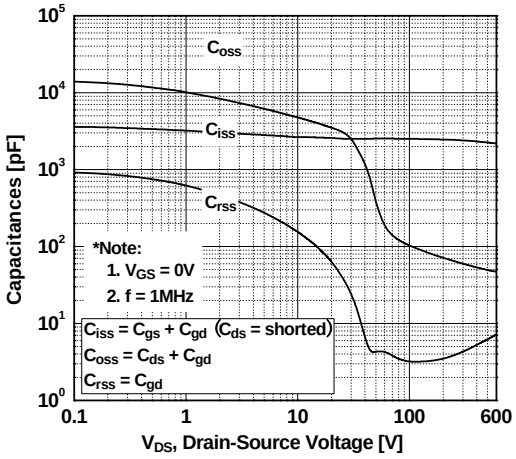
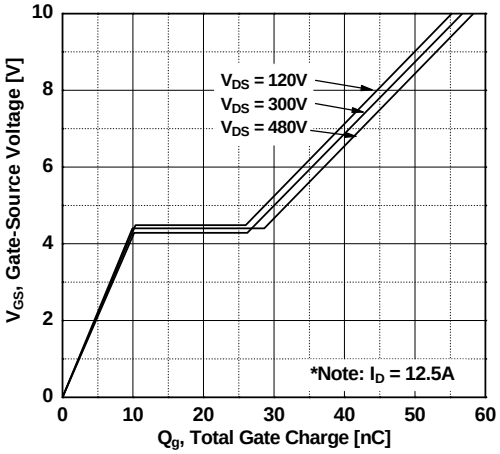


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

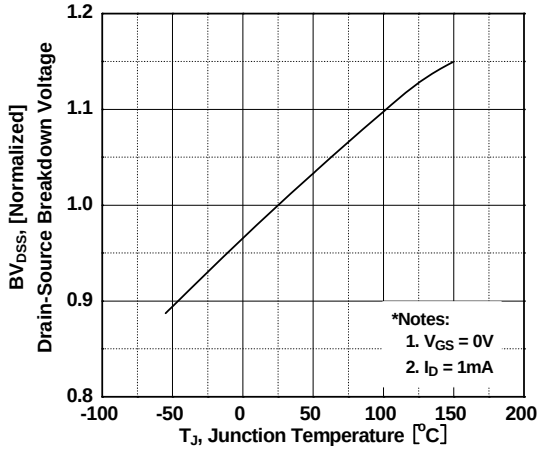


Figure 8. On-Resistance Variation vs. Temperature

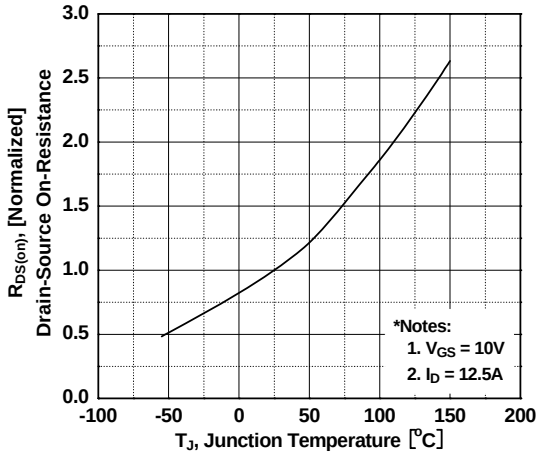


Figure 9. Maximum Safe Operating Area

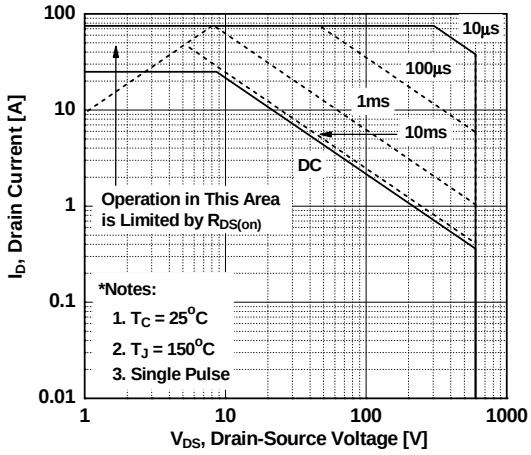


Figure 10. Maximum Drain Current vs. Case Temperature

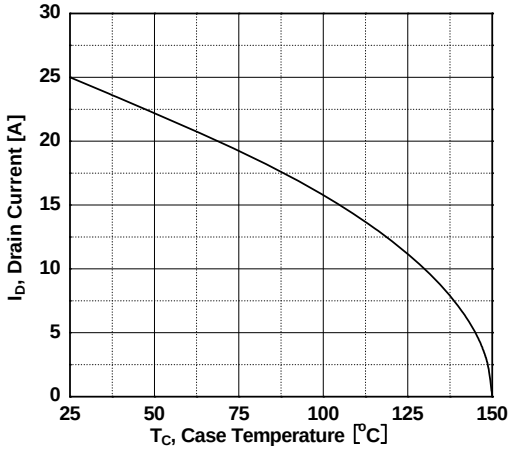
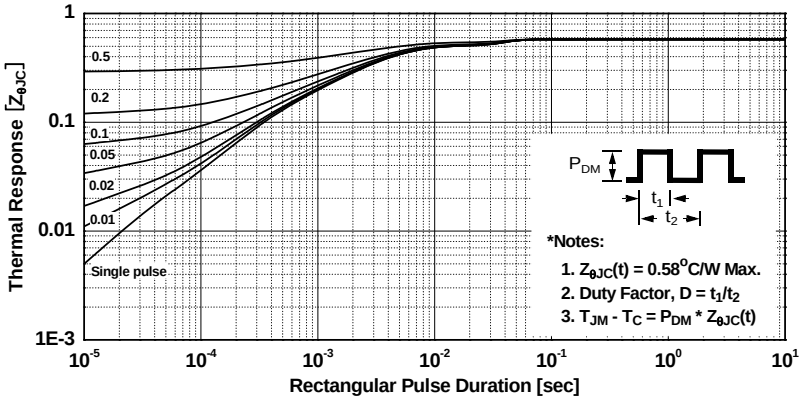
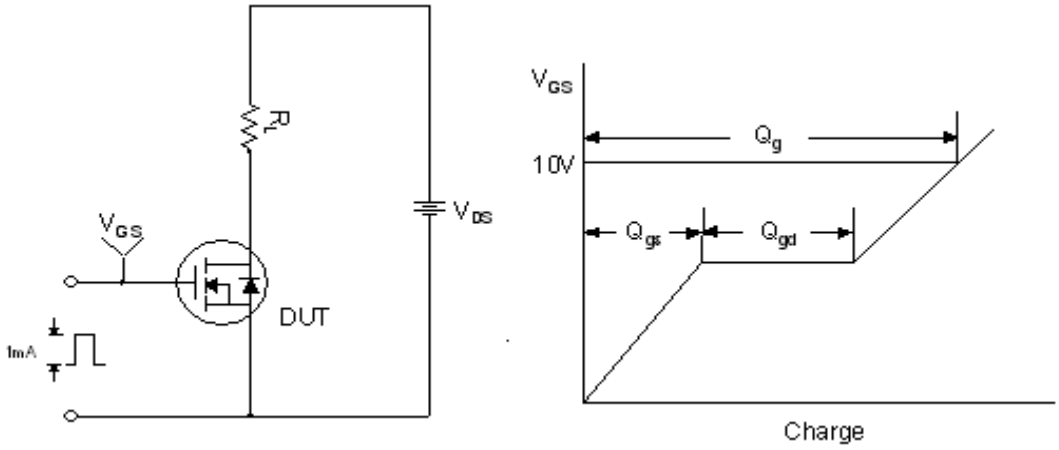


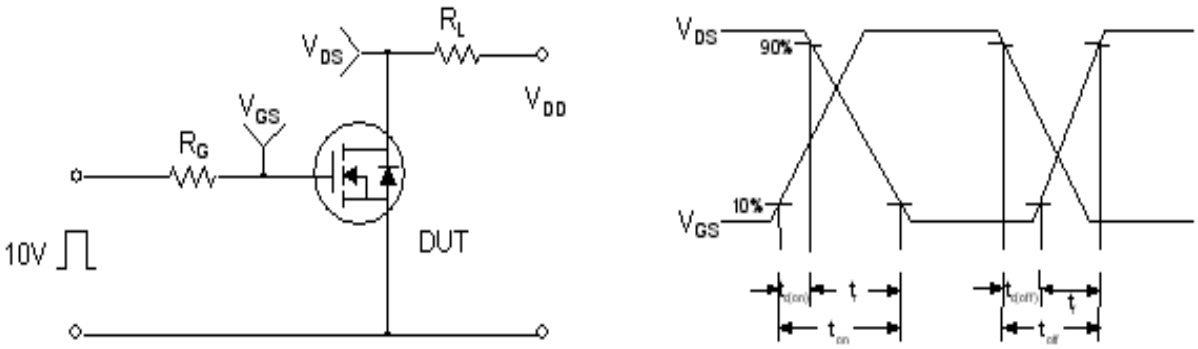
Figure 11. Transient Thermal Response Curve



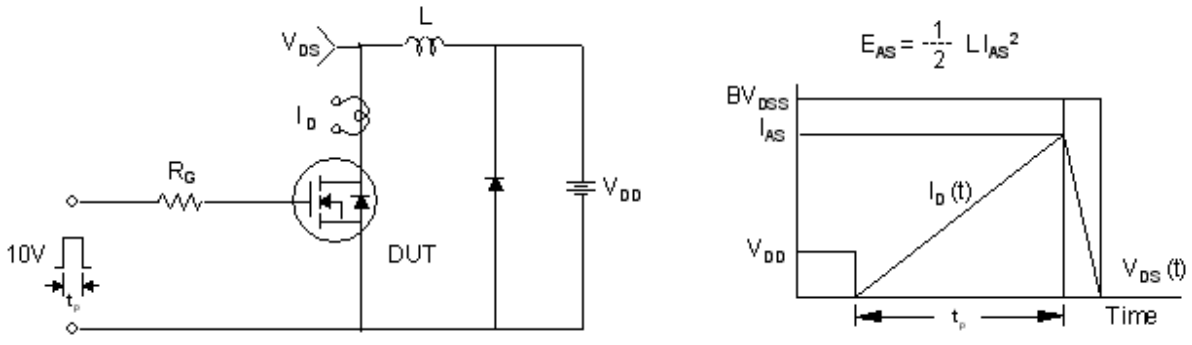
Gate Charge Test Circuit & Waveform



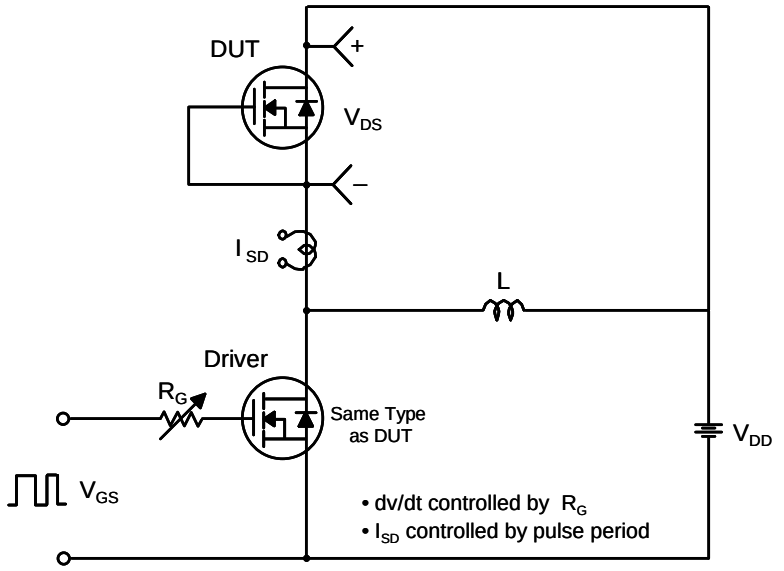
Resistive Switching Test Circuit & Waveforms

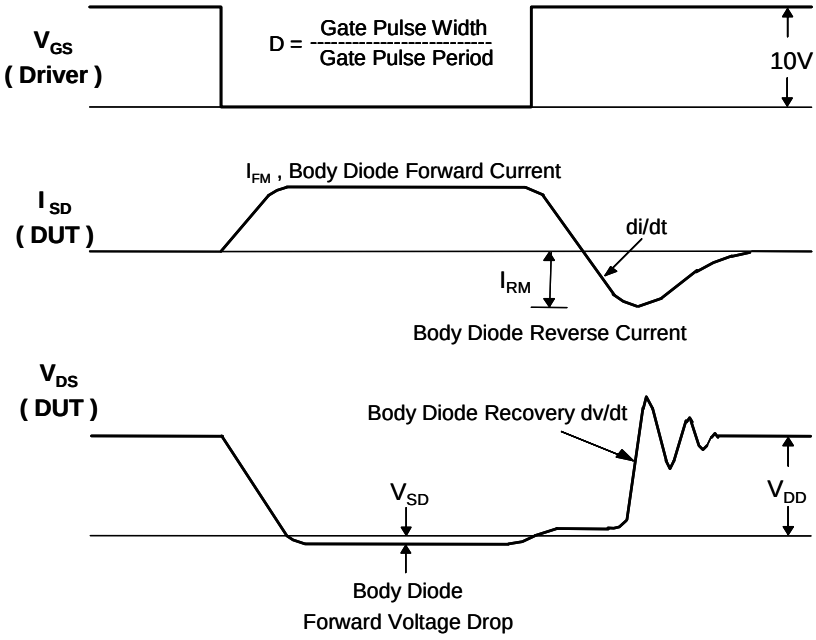


Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms





Mechanical Dimensions

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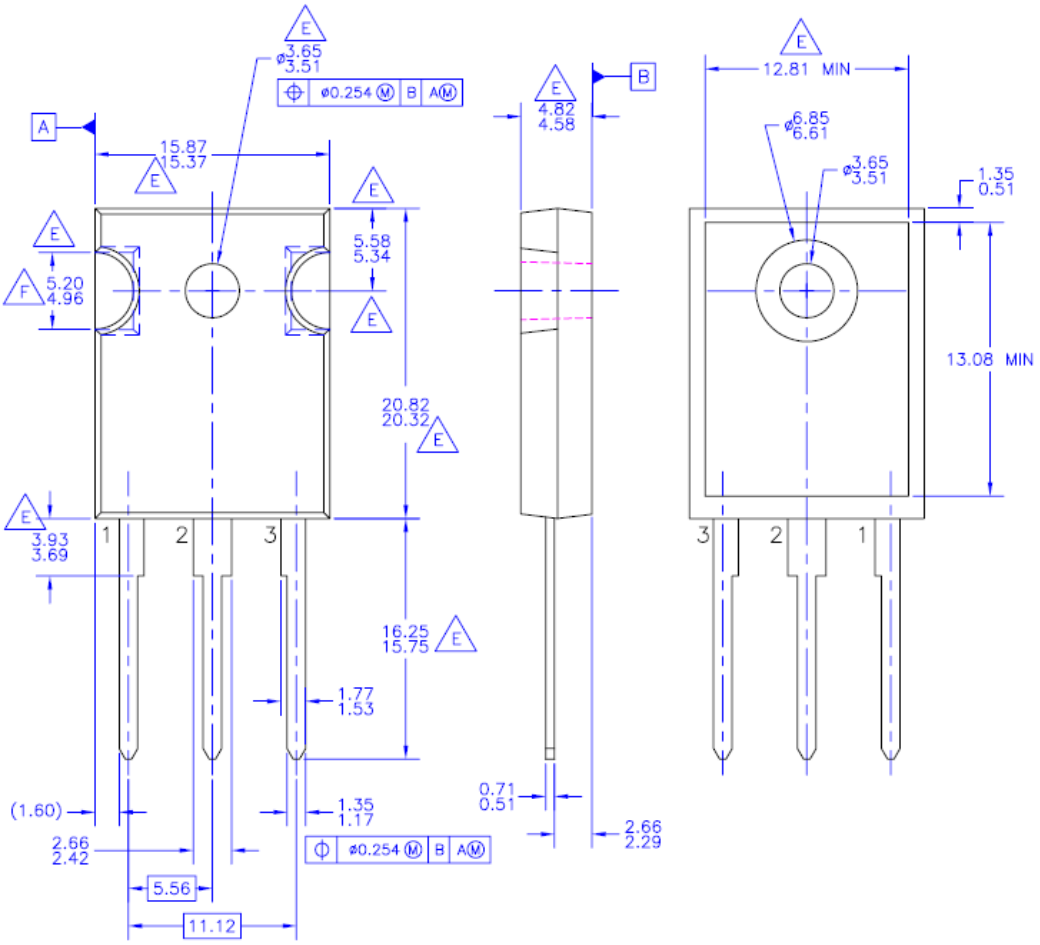

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F. NOTCH MAY BE SQUARE

G. DRAWING FILENAME: MKT-TO247A03_REV02

Dimensions in Millimeters

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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
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